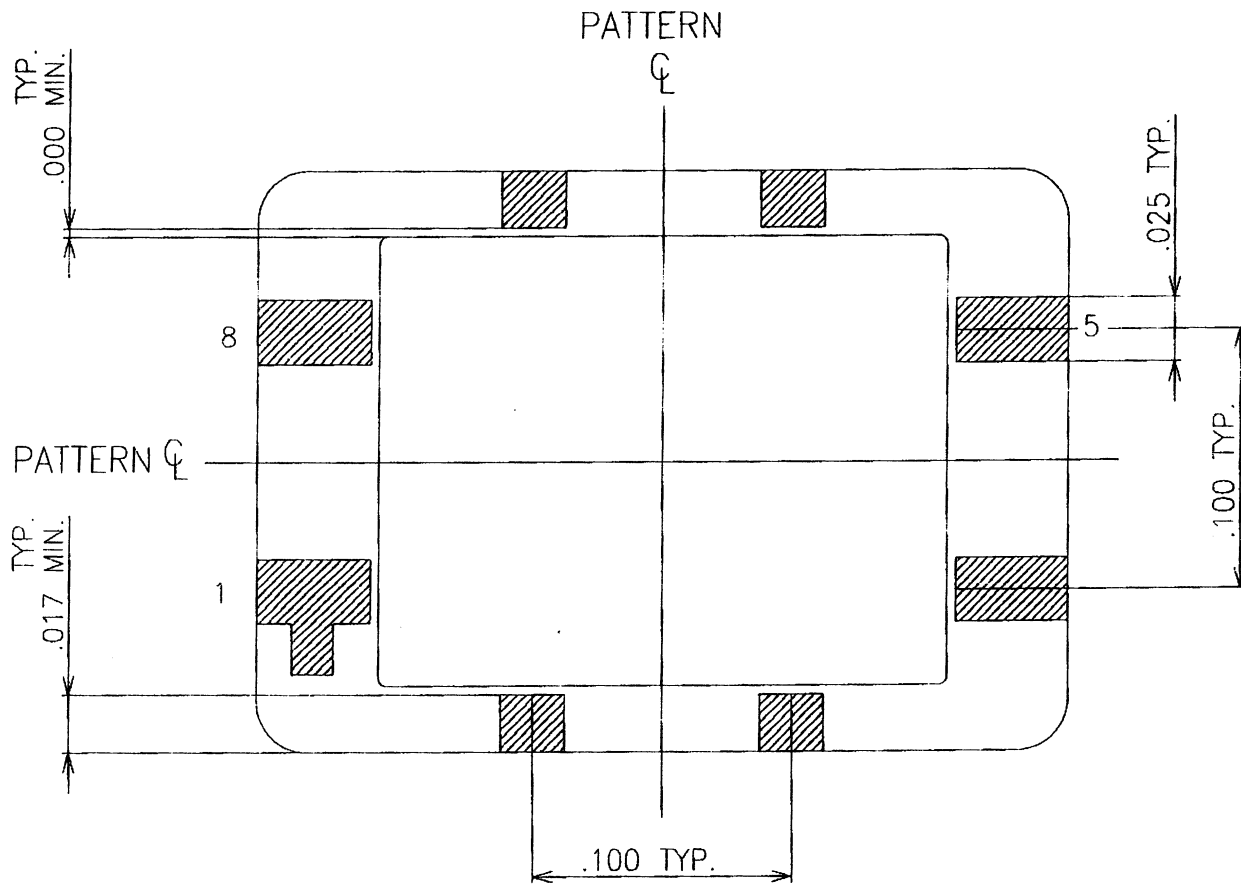


NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.20 OHM MAX.

MULTIPLIER					NAME	8 LEAD SIDE BRAZED PACKAGE	TOLERANCE	SB008AK959-1			S=0
					SCALE	7/1	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
					MATERIAL	AS INDICATED	THIRD ANGLE PROJECTION	T.S/H.K.	H.S/S.NI	H.SA	JUN.26.'01
								DRAWING NO.			SHEET
CHANGED				DATE	DRAWN	CHECKED	APPROVED	KD-SA1959			1/5
					KYOCERA		KYOCERA CORPORATION		KYOTO JAPAN		



BONDING PATTERN

MULTI LEVELS	DATE	DRAWN	CHECKED	APPROVED	NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	T.S/H.K.	H.S/S.NI	H.SA	JUN.28.'01
CHANGED	DATE	DRAWN	CHECKED	APPROVED	SCALE	MATERIAL	THIRD ANGLE PROJECTION		DRAWING NO.	SHEET
					20 / 1				KD-SA1959	2 / 5
					KYOCERA	KYOCERA CORPORATION KYOTO JAPAN				